

# 2027 2nd International Conference on Electromagnetic Engineering & Microwave Systems

**June 11-13, 2027** **Hangzhou, China**

EEMS 2027

www.iceems.org

Taking place from June 11 to 13, 2027 2nd International Conference on Electromagnetic Engineering & Microwave Systems (EEMS) will be held in Hangzhou, China. Co-sponsored by Yangtze Delta Region Academy of Beijing Institute of Technology (Jiaxing), Zhejiang University, Hangzhou Dianzi University, and Ningbo University, the conference aims to fully leverage Hangzhou's unique strengths in fostering innovation, creating a world-class international exchange platform that brings together global academics, industry leaders, and technology innovators. It will serve as a dynamic venue for sharing cutting-edge insights, building cross-border collaboration networks, and driving technological advancements in the fields of electromagnetic engineering and microwave systems.

## CALL FOR PAPERS:

### Track 1: Microwave Devices and Circuit Design

**Track Chair:**



**Prof. Li Yang**
**South China University of Technology, China**

Modeling and Design of Active/Passive Devices

Design of Power Amplifiers and Low-Noise Amplifiers

Design of Microwave/Millimeter-Wave Integrated Circuits (MMIC/RFIC)

Design of Filters, Couplers and Power Dividers

Reconfigurable and Tunable Microwave Circuits

Microwave Devices Based on Wide Bandgap Semiconductors

Terahertz Devices and Circuit Design

Low-Power Microwave/RF Device Design

More information about topics, please visit: *https://www.iceems.org/cfp.html*

## SUBMISSION

The manuscript in double-column format should have at least 4 full pages and up to 10 pages. If it exceeds 5 pages, the extra page(s) will be charged. Manuscripts must be written in English and follow the instructions at Manuscript Formatting and Templates. Submission system: *http://easychair.org/conferences/?conf=eems2027*

## PUBLICATION

All submissions will be sent for double-blind review. Accepted papers with registration and presentation will be published in Conference Proceedings.

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## IMPORTANT DATES

Submission Deadline: January 10th, 2027
Notification Date: February 10th, 2027
Registration Deadline: February 25th, 2027
Camera Ready: February 25th, 2027

## CONTACT US

Conference secretary: Ms. Sia Liu
Email Address: eems_conf@163.com

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